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L28: Entry 1 of 1

File: DWPI

Oct 12, 1985

DERWENT-ACC-NO: 1985-293138

DERWENT-WEEK: 198547

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TITLE: Dry etching appts. - has circular wafer bed contg. integrated ring part of material deactivating used etchant

PATENT-ASSIGNEE:

ASSIGNEE	CODE
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PRIORITY-DATA: 1984JP-0058602 (March 27, 1984)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP <u>60201632</u> A	October 12, 1985		004	
JP 93023053 B	March 31, 1993		004	H01L021/302

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP 60201632A	March 27, 1984	1984JP-0058602	
JP 93023053B	March 27, 1984	1984JP-0058602	
JP 93023053B		<u>JP 60201632</u>	Based on

INT-CL (IPC): C23F 4/00; H01L 21/30; H01L 21/302

ABSTRACTED-PUB-NO: JP 60201632A

BASIC-ABSTRACT:

Appts. for etching a wafer base plate with a reactive gas-plasma is described in which a wafer is set on a supporting electrode put in a reaction container and etched with an etchant of a reactive gas or its activated or ionised gas. A circular wafer bed is placed on the surface of the supporting electrode, the bed being concentric with the wafer and having a dia. smaller than its orientation flat. A ring part made of a material capable of deactivating the action of the used etchant is integrated with the wafer bed, the ring part having an inner dia. which is almost same as the outer dia. of the wafer bed, having a height which is almost same as that of the wafer bed and having an outer dia. which is larger than that of the wafer.

USE/ADVANTAGE - The action of the used etchant near the part of the orientation flat of a wafer to be etched may be reduced or controlled, whereby all the surface of the wafer may be etched uniformly.

CHOSEN-DRAWING: Dwg. 0/3

TITLE-TERMS: DRY ETCH APPARATUS CIRCULAR WAFER BED CONTAIN INTEGRATE RING PART MATERIAL DEACTIVATE ETCH

DERWENT-CLASS: L03 M14 U11

CPI-CODES: L03-D03C; M14-A;